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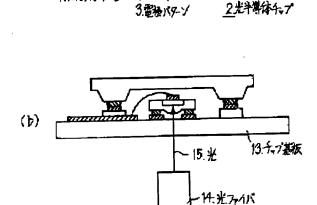
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TITLE

PRODUCTION OF OPTICAL

SEMICONDUCTOR DEVICE



7治性部間をパターン 6.活性部

5紀線性気密リング

1地服板

[]<sup>18</sup> 747

はばがソブ 8

ABSTRACT:

PURPOSE: To shorten the processing stage by integrally and simultaneously executing hermetic sealing of many pieces of optical semiconductor chips in the process for production of a light emitting device and a light receiving device for optical communication formed by using the optical semiconductor chips and more particularly hermetic sealing of the optical semiconductor chips into the optical semiconductor device.

CONSTITUTION: A gap 10 having projecting parts 12 two-dimensionally formed in correspondence to insulating rings 5 on the rear surface is aligned and soldered to a transparent substrate 1 formed by two-dimensionally arranging the plural optical semiconductor chips 2 on the transparent substrate 1 and is soldered to integrally and hermetically seal the plural optical semiconductor chips 2. Further, an optical fiber device having a light reflecting means for bending the light 15 emitted from an optical fiber 14 in the direction perpendicular to the optical axis of the optical fiber 14 is adhered to the transparent substrate 1.

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